PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4045114

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MASAYOSHI IMAI	09/05/2016
SATOMI HAMADA	09/05/2016

RECEIVING PARTY DATA

Name:	EBARA CORPORATION	
Street Address:	11-1 HANEDA ASAHI-CHO	
Internal Address:	OHTA-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	144-8510	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15186352

CORRESPONDENCE DATA

Fax Number: (215)568-3439

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 215-568-3100

Email: assignments@bakerlaw.com **Correspondent Name: BAKER & HOSTETLER LLP** Address Line 1: CIRA CENTRE 12TH FLOOR

Address Line 2: 2929 ARCH STREET

Address Line 4: PHILADELPHIA, PENNSYLVANIA 19104-2891

ATTORNEY DOCKET NUMBER:	101716.000141
NAME OF SUBMITTER:	DACIA J. HERNANDEZ
SIGNATURE:	/Dacia J. Hernandez/
DATE SIGNED:	09/09/2016

Total Attachments: 4

source=Executed_Assignments#page1.tif source=Executed_Assignments#page2.tif source=Executed_Assignments#page3.tif

> **PATENT REEL: 039687 FRAME: 0809** 503998458

source=Executed_Assignments#page4.tif

PATENT REEL: 039687 FRAME: 0810

ASSIGNMENT

WHEREAS, I, Masayoshi IMAI, a citizen of Japan, residing at c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan, ASSIGNOR, am an inventor of one or more inventions disclosed, described and/or claimed in the application referred to as Docket Number 101716.000141 ("the invention"), which is entitled "WAFER DRYING APPARATUS AND WAFER DRYING METHOD" ("the subject application"), and which claims priority to Japanese patent application number 2015-124538 filed June 22, 2015 ("the priority application"). I authorize and direct any of the attorneys responsible for prosecuting the subject application on behalf of the ASSIGNEE to insert the application number and filing date of the subject application in the final paragraph of this assignment.

AND WHEREAS, EBARA CORPORATION, ASSIGNEE, having a place of business at 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan, is desirous of obtaining my entire right, title, and interest in, to, and under the invention:

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, hereby sell, assign, transfer, and set over, unto the ASSIGNEE, its successors, legal representatives, and assigns, my entire right, title, and interest in, to, and under the invention, and all applications for industrial property protection, including without limitation, all applications for patents, utility models, inventors' certificates, and designs that have been filed, and that may hereafter be filed, in any country, that disclose, describe, and/or claim the invention, including, without limitation, the subject application and the priority application, and all extensions, renewals, and reissues of such applications, including all divisions and continuations in whole or in part; all patents granted on such applications in any country, and all extensions, renewals, and reissues of such patents, including all divisions and continuations in whole or in part; the right to file such applications in any country; and the right to claim for such applications in any country the priority rights derived from the priority application and the subject application under the International Convention for the Protection of Industrial Property, the Patent Laws of the United States, any other international agreement or protection, or the domestic laws of any country in which any such application is filed, as may be applicable.

AND I HEREBY covenant and agree that I have full right to convey my entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the ASSIGNEE, its successors, legal representatives, and assigns, any facts known to me respecting the invention, and testify in any legal proceeding, sign all lawful papers, execute all disclaimers and all divisional, continuing, reissue, and foreign applications, make all rightful oaths, deliver upon request all papers, documents, affidavits, or other instruments that may be necessary or helpful in the prosecution of any application for industrial property protection describing and/or claiming

the invention, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives, and assigns, to obtain and enforce proper protection for the invention in all countries.

IN TESTIMONY WHEREOF, I have signed my name below on the date indicated above my signature.

1	2016
Executed this5th	day of <u>September</u> , year of <u>2016</u> .
######################################	
STATEMENT OF WI	ITNESS
(City)	(Country)
This day of	, 201
Į,	whose full
residence address is	
was personally presented and day of person described in suc	t and did see execute the above assignment on the, 201, and such assignor is personally known to me to be the sh document.
Signature of Witness	
********	*************************
The foregoing assignm June 17, 2016 .	ent covers patent application number 15/186,352 , filed on
	/Michael J. Swope/
	Name of Attorney: Michael J. Swope Registration No.: 38,041

Date of Insertion: September 9, 2016

Page 2 of 2

ASSIGNMENT

WHEREAS, I, Satomi HAMADA, a citizen of Japan, residing at c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan, ASSIGNOR, am an inventor of one or more inventions disclosed, described and/or claimed in the application referred to as Docket Number 101716.000141 ("the invention"), which is entitled "WAFER DRYING APPARATUS AND WAFER DRYING METHOD" ("the subject application"), and which claims priority to Japanese patent application number 2015-124538 filed June 22, 2015 ("the priority application"). I authorize and direct any of the attorneys responsible for prosecuting the subject application on behalf of the ASSIGNEE to insert the application number and filing date of the subject application in the final paragraph of this assignment.

AND WHEREAS, EBARA CORPORATION, ASSIGNEE, having a place of business at 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan, is desirous of obtaining my entire right, title, and interest in, to, and under the invention:

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, hereby sell, assign, transfer, and set over, unto the ASSIGNEE, its successors, legal representatives, and assigns, my entire right, title, and interest in, to, and under the invention, and all applications for industrial property protection, including without limitation, all applications for patents, utility models, inventors' certificates, and designs that have been filed, and that may hereafter be filed, in any country, that disclose, describe, and/or claim the invention, including, without limitation, the subject application and the priority application, and all extensions, renewals, and reissues of such applications, including all divisions and continuations in whole or in part; all patents granted on such applications in any country, and all extensions, renewals, and reissues of such patents, including all divisions and continuations in whole or in part; the right to file such applications in any country; and the right to claim for such applications in any country the priority rights derived from the priority application and the subject application under the International Convention for the Protection of Industrial Property, the Patent Laws of the United States, any other international agreement or protection, or the domestic laws of any country in which any such application is filed, as may be applicable.

AND I HEREBY covenant and agree that I have full right to convey my entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the ASSIGNEE, its successors, legal representatives, and assigns, any facts known to me respecting the invention, and testify in any legal proceeding, sign all lawful papers, execute all disclaimers and all divisional, continuing, reissue, and foreign applications, make all rightful oaths, deliver upon request all papers, documents, affidavits, or other instruments that may be necessary or helpful in the prosecution of any application for industrial property protection describing and/or claiming

the invention, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives, and assigns, to obtain and enforce proper protection for the invention in all countries.

IN TESTIMONY WHEREOF, I have signed my name below on the date indicated above my signature.

, ,	
Executed this5th	day of <u>September</u> , year of <u>2016</u> .
	MADA) ***********************************
STATEMENT OF W SIGNED at	TTNESS
(City)	(Country)
This day of	, 201
I,	whose full
residence address is	
was personally presen day of person described in suc	t and did see execute the above assignment on the, 201, and such assignor is personally known to me to be the ch document.
Signature of Witness	
*******	*************************
The foregoing assignm June 17, 2016 .	nent covers patent application number 15/186,352 , filed on
	/Michael J. Swope/
	Name of Attorney: Michael J. Swope
	Registration No.: 38,041

Date of Insertion: September 9, 2016

Page 2 of 2

PATENT REEL: 039687 FRAME: 0814